9. **(Amended)** The latex for dip molding according to claim 1, wherein the emulsion polymerization of the monomer mixture is carried out in the presence of a seed polymer having an average particle diameter of 10 to 90 nm and a glass transition temperature (Tg) of -50 to 50°C obtained by emulsion polymerization of a vinyl cyanide monomer and an ethylenically unsaturated monomer copolymerizable therewith.

10. **(Amended)** A dip molded product produced by dip molding from the latex for dip molding described in claim 1.